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| HONDA TSUSHIN KOGYO CO., LTD. TOKYO JAPAN | | Sheet | 1 OF 2 | |
| | | Date issued | MAR 26, 2002 | |
| Product Specification <u>Solder dip Male type for PC-Board</u> | | Approved by | Checked by | Prepared by |
| | | <i>K. Narumo</i> K.NARUMO | <i>K. Hasumi</i> K.HASUMI | <i>N. Taoka</i> N.TAOKA |
| 1. Connector Part Number | | | | |
| Type | | Connector Part No. | | |
| Male Connector | | Z-148, Z-149, Z-152,Z-152A (DIC-148, DIC-149, DIC-152,DIC-152A) | | |
| Female Connector | | Z-128, Z-129 (DIC-128, DIC-129) | | |
| 2. Connector characteristics | | | | |
| No. | Item | Specification | | |
| 1 | Current Rating | 1 amp DC maximum per contact | | |
| 2 | Voltage Rating | 125 volts AC (r.m.s.) | | |
| 3 | Operating Temperature | -25 degree C~80 degree C | | |
| 4 | Operating Humidity | 85% maximum | | |
| 5 | Structure,Form,Dimension | When tested in accordance with JIS C 5402 test 4.1,conform to referenced drawings. | | |
| 6 | Meterial,Finish | When tested in accordance with JIS C 5402 test 4.2,conform to referenced drawings. | | |
| 7 | Indication | When tested in accordance with JIS C 5402 test 4.4,conform to referenced drawings. | | |
| 8 | Mating | When tested in accordance with JIS C 5402 test 4.3,unite with compatible connector. | | |
| 9 | Insulation Resistance | When tested in accordance with method C of JIS C 5402 test 5.2, the insulation resistance shall be a minimum of 1000 M Ω at 500 volts DC. | | |
| 10 | Dielectric Withstanding Voltage | When tested in accordance with method C of JIS C 5402 test 5.1, there shall be no breakdown of insulation or flashover at 1000 volts AC (r.m.s.) for a minute. | | |
| 11 | Contact Resistance | _____ | | |
| 12 | Female Contact Insertion and Withdrawal Force (Individual) | _____ | | |
| 13 | Connector Insertion and Withdrawal Force (Overall) | _____ | | |
| 14 | Humidity | <p>When tested in accordance with JIC C 5402 test 7.3 , there shall be no evidence of cracking of the body or other physical damage to the connector. After test the insulation resistance shall be a minimum of 100 MΩ at 500 volts DC and dielectric withstanding voltage shall be no breakdown of insulation or flashover at 1000 volts AC (r.m.s.) for a minute.</p> <p>Humidity : 90% Test duration : 96 hours Temperature : 40 degree C</p> | | |

| No. | Item | Specification |
|---|------------------------------------|---|
| 15 | Temperature Cycling | When tested in accordance with JIS C 5402 test 7.2 (Temperature : -55 degree C~+85 degree C), there shall be no evidence of cracking of the body or other physical damage to the connector. |
| 16 | Vibration | When tested in accordance with JIS C 5402 test 6.1 (10 Hz to 55Hz, Amplitude:1.52mm,Acceleration:98m/s ²), there shall be no physical or mechanical damage to the connector. |
| 17 | Shock | When tested in accordance with JIS C 5402 test 6.2 (Acceleration: 490m/s ²), there shall be no physical or mechanical damage to the connector |
| 18 | Mechanical Operation (Durability) | _____ |
| 19 | Corrosion (Salt spray) | When tested in accordance with JIS C 5402 test 7.1 (Temperature: +35 degree C , Concentration : 5% , Duration : 48 hours), there shall be no evidence of cracking of the body or other physical damage to the connector. |
| 20 | Resistance to H ₂ S Gas | When tested in accordance with JEIDA-38 , there shall be no physical or mechanical damage to the connector. H ₂ S gas concentration : 3 ppm Temperature : 40 degree C Test Time : 48 hours |
| 21 | Resistance to Solder Heat | When tested in accordance with method 208E MIL-STD-202F(flow temperature 260 degree C , dipping time 5 sec), a through hole board with thickness of 1.6mm contact termination area should be soldered correctly to the pad in PC board without any damage on the every part of connector. |
| 22 | Solder ability | When tested in accordance with JIS C 5402 test 7.11 (flow temperature 260 degree C , dipping time 5 sec), after the test, appearance the termination is 90% covered by a continuous solder coating. |
| <p>Notes of soldering work</p> <ol style="list-style-type: none"> 1. Flux should use the rosin system of noncorrosive. 2. Preheating should be controlled under 100 degree C. 3. Flow temperature under 260 degree C, dipping time under 5 sec. 4. After flow solder should surely perform flux washing. Washing liquid : freon system, alcohol system, chlorosol system 5. Please remove a conformity connector in the case of soldering. <p>Note Refer to the product specification of a conformity connector about the item of No.#11,12,13,18,19,20.</p> | | |